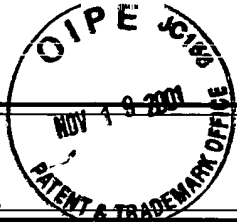


2812



TRANSMITTAL LETTER
(General - Patent Pending)

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Docket No.
END920010002US1

In Re Application Of: **Ray et al.**

NOV 20 2001
TC 2000 MAIL ROOM

Serial No.	Filing Date	Examiner	Group Art Unit
09/779,812	2/8/01	Nguyen, H.	2812

Title: **LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE**

TO THE COMMISSIONER OF PATENTS AND TRADEMARKS:

Transmitted herewith is:

Response to Restriction Requirement

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of _____ is attached.
- ☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. **09-0457(IBM)** as described below. A duplicate copy of this sheet is enclosed.
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Jack P. Friedman

Signature

Dated: **10-17-2001**

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I certify that this document and fee is being deposited on 10/17/01 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.
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